



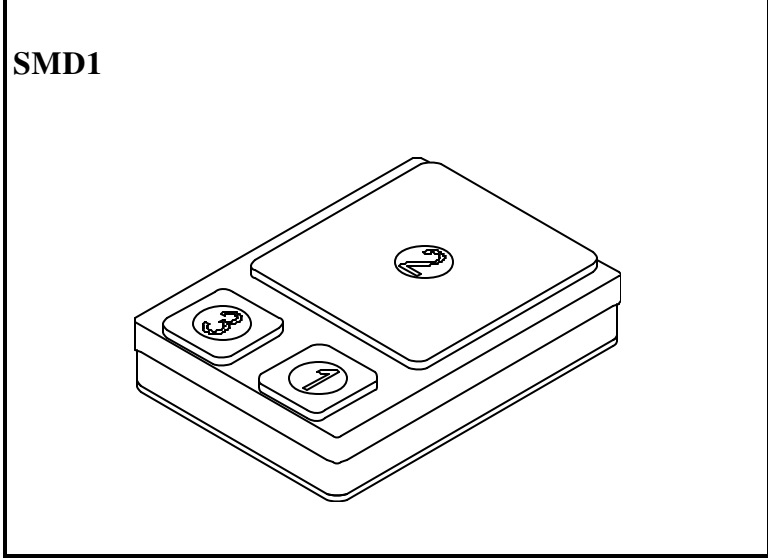
Solid State Devices, Inc.

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**SDR623CTS1
 Thru
 SDR626CTS1**

**40A 35nsec 300-600 V
 Hyper Fast Centertap Rectifier**

DESIGNER'S DATA SHEET ^{1/}



- Features:**
- Hyper Fast Recovery: 35nsec Maximum ^{3/}
 - High Surge Rating
 - Low Reverse Leakage Current
 - Low Junction Capacitance
 - Hermetically Sealed Surface Mount Package
 - Gold Eutectic Die Attach
 - Ultrasonic Aluminum Wire Bonds
 - TX, TXV, and S-Level Screening Available ^{2/}

Maximum Ratings		Symbol	Value	Units
Peak Repetitive Reverse Voltage	SDR623CTS1	V_{RRM}	300	Volts
	SDR624CTS1	V_{RWM}	400	
	SDR625CTS1	V_R	500	
	SDR626CTS1		600	
Average Rectified Forward Current ^{4/} (Resistive Load, 60 Hz Sine Wave, $T_A = 25^\circ C$)		I_o	40	Amps
Peak Surge Current ^{5/} (8.3 ms Pulse, Half Sine Wave, $T_A = 25^\circ C$)		I_{FSM}	200	Amps
Operating & Storage Temperature		$T_{OP} \& T_{STG}$	-65 to +200	$^\circ C$
Maximum Total Thermal Resistance		$R_{\theta JC}$	1.3	$^\circ C/W$
Junction to Case ^{4/}			2.3	
Junction to Case ^{5/}				

Notes:

1/ For ordering information, Price, Operating Curves, and Availability- Contact Factory.
 2/ Screened to MIL-PRF-19500.
 3/ Recovery Conditions: $I_F = 0.5$ Amp, $I_R = 1.0$ Amp, rec. to .25 Amp.
 4/ Both Legs Tied Together.
 5/ Each Leg.



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Electrical Characteristics, per leg	Symbol	Max	Units	
Instantaneous Forward Voltage Drop ($I_F = 10\text{Adc}$, Pulse)	$T_A = 25\text{ }^\circ\text{C}$	V_{F1}	1.35	V_{DC}
	$T_A = 25\text{ }^\circ\text{C}$	V_{F2}	1.50	
Instantaneous Forward Voltage Drop ($I_F = 10\text{Adc}$, Pulse)	$T_A = 100\text{ }^\circ\text{C}$	V_{F3}	1.25	V_{DC}
	$T_A = -55\text{ }^\circ\text{C}$	V_{F4}	1.45	
Reverse Leakage Current (100% of rated V_R , Pulse)	$T_A = 25\text{ }^\circ\text{C}$	I_{R1}	50	μA
	$T_A = 100\text{ }^\circ\text{C}$	I_{R2}	5	mA
Reverse Recovery Time ($I_F = 0.5\text{A}$, $I_R = 1\text{A}$, $I_{RR} = 0.25\text{A}$, $T_A = 25\text{ }^\circ\text{C}$)		t_{RR}	35	nsec
Junction Capacitance ($V_R = 10V_{DC}$, $T_A = 25\text{ }^\circ\text{C}$, $f = 1\text{MHz}$)		C_J	150	pF

PIN ASSIGNMENT			
PACKAGE	Pin 1	Pin 2	Pin 3
SMD1	Anode	Cathode	Anode

SMD1 Outline:

The 2D drawing shows a rectangular package with a height of .140". The top surface features two small square pads, each .140" wide and .035" MIN apart. The distance from the left edge to the center of the first pad is .050". The pads are .030" MIN high. The main body of the package is .415" high and .375" wide. The bottom surface has a .037" wide lead. The total width of the package is .450".

Tolerances
 Unless Specified- .XX ± .020"
 .XXX ± .010"